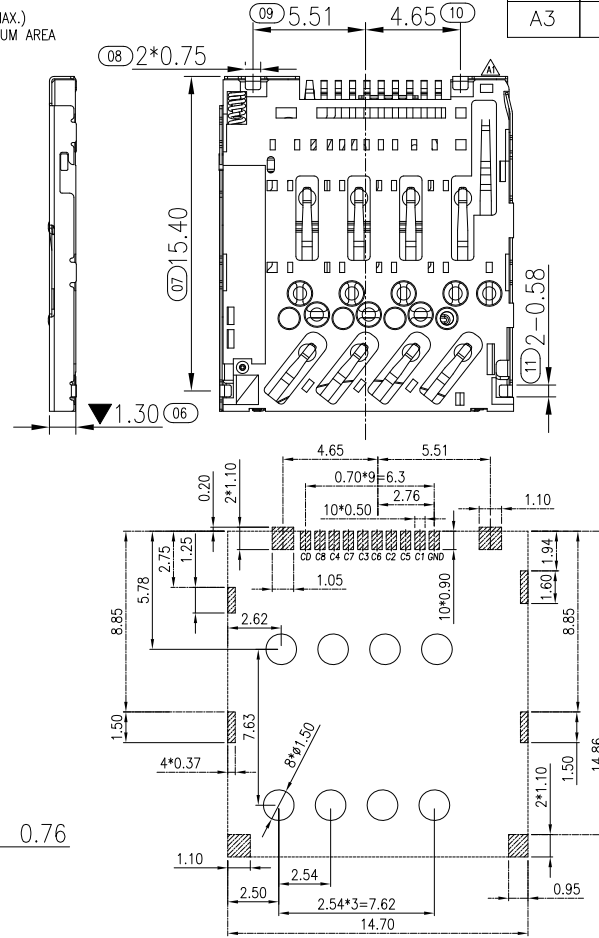


[illegible]

 :NO WIRING AREA
 :BOARD PAD
 NOTE 1:  :PCB through hole

Figure 5.2 RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

Matrix
Micro SIM

MSM-01-01-10-13-36

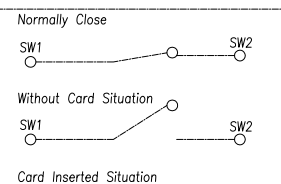
01 : Push
02 : Non-Push

Plating
01:G/F

Series Number

Height

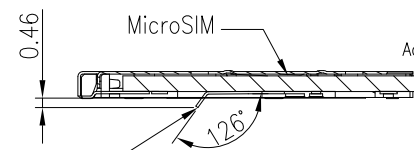
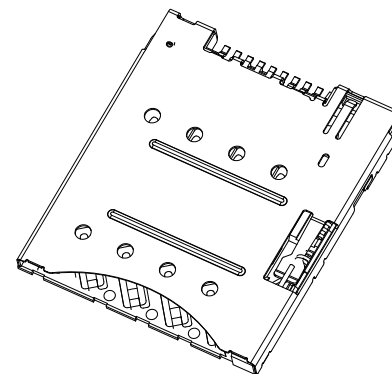
Pin number
10:10pin



REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2017/05/08	Phebe Su
A1			取消开关处压料孔	2017/09/18	Phebe Su
A2			Add the focus size mark	2017/12/01	Phebe Su
A3			Correct terminals and plastic structure	2017/12/18	Phebe Su

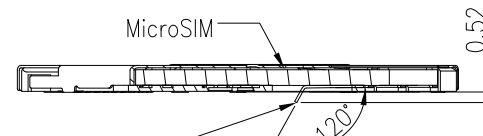
Insulator: High Temperature Thermoplastic,UL 94V-0.
Contact: Copper Alloy
Shell: STAINLESS
PLATING :
TERMINAL:
CONTACT AREA: GOLD OR NICKEL.
SOLDER AREA: MATTE TIN 80U" PLATED.
SHELL: GOLD OR NICKEL.
SOLDER AREA: GOLD FLASH.

Current Rating :1A max.
Voltage Rating :30V DC MAX
Ambient Temperature Range :-40°C~+85°C
Storage Temperature Range :-40°C~+85°C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100mΩ max.
Insulation Resistance:1000MΩ min./500V DC
Dielectric Withstanding Voltage:500V AC
Mating Cycles:5,000 Insertions
Temperature: 260°C ±5°



The ends of the terminals reveal the outer surface of the product

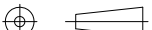
SEC A-A



The ends of the terminals reveal the outer surface of the product

SEC A-A

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved
SW1	C/D
SW2	GND

NO	VARIETY	QTY	MATERIAL	REMARK
 Matrix Electronics Co.,Ltd				
TOLERANCE: X: X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 ANGLE: ±3°		DESIGN BY : Phebe Su	DATE : 2017/12/18	PART NAME: Micro SIM card 1.3H
		CHECKED BY: Janice Liu	DATE : 2017/12/18	PART NO. MSM-01-01-10-13-3
 UNIT: mm [inch]		APPROVED BY1: Richard Hsieh	DATE : 2017/12/18	MOLD NO. NA
		APPROVED BY2: Richard Hsieh	DATE : 2017/12/18	DRAW NO.
SCALE: 1:1 SIZE: A4			SHEET NO. 1 OF 1	